

DOCKET NO: 260055US26SP PCT

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF :  
TAKEHIRO UEDA, ET AL. : EXAMINER: DAHIMENE, M.  
SERIAL NO: 10/509,338 :  
FILED: OCTOBER 8, 2004 : GROUP ART UNIT: 1792  
FOR: METHOD FOR SUPPRESSING :  
CHARGING OF COMPONENT IN  
VACUUM PROCESSING CHAMBER OF  
PLASMA PROCESSOR AND PLASMA  
PROCESSOR

STATEMENT OF SUBSTANCE OF INTERVIEW UNDER MPEP § 713.04

COMMISSIONER FOR PATENTS  
ALEXANDRIA, VIRGINIA 22313

SIR:

As a result of the interview conducted on June 11, 2009, please amend the above-identified application as follows:

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks** begin on page 4 of this paper.

IN THE CLAIMS

Please amend the claim as follows:

Claim 1 (Currently Amended): A semiconductor device manufacturing method using a plasma processor, ~~the~~ wherein said plasma processor includes~~[,]] comprising:~~

a vacuum processing chamber in which plasma is generated to plasma-process an object to be processed;

a block having a flow path of a heat medium in an inner part thereof; and

a component in the vacuum processing chamber disposed to be in contact with the block and made at least partly of an insulative material, and

wherein said plasma processor controls ~~a controlling~~ temperature of the component in the vacuum processing chamber by circulating an insulating fluid as the heat medium in the flow path, and

said method comprising:

carrying the object to be processed into the vacuum processing chamber, generating plasma to plasma-process the object to be processed, and carrying the object to be processed that has undergone the processing out of the vacuum processing chamber; ~~and~~

between said processing of the object to be processed and processing of a subsequent object to be processed, circulating the insulating fluid in the flow path while the object to be processed is not in the vacuum processing chamber and no plasma is generated, and controlling pressure in the vacuum processing chamber to a predetermined pressure while supplying inert gas as a purging gas into the vacuum processing chamber~~[,]] ;~~ and

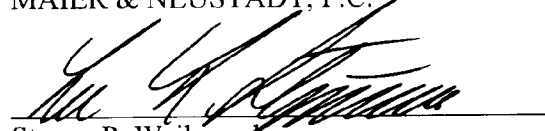
~~wherein~~ determining and applying a pressure of said inert gas is ~~determined~~ on a Paschen's curve so that electrical charging of the component in the vacuum processing chamber is suppressed.

REMARKS/ARGUMENTS

A telephone interview was conducted with Examiner Dahimene on June 10, 2009, and a follow-up interview was conducted on June 11, during which, the attached examiner's amendment was discussed. Applicants provided authorization for the attached examiner's amendment on June 11, 2009. Applicants respectfully submit that the above-noted comments, along with the attached proposed examiner's amendment to Claim 1, qualify as a statement of substance of interview under MPEP § 713.04.

Respectfully submitted,

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